



DUPONT AS300

SILVER CONDUCTOR

PRODUCT DESCRIPTION

The DuPont™ AS series of thick film pastes is suitable for applications where thermal management is crucial to performance of the circuit. AS300 is a silver paste for screen printing of conductive interconnect layers on aluminum substrates and heat sinks for construction of high thermal conductivity interfaces for LED lighting and power components.

KEY FEATURES

- High solder adhesion
- Wire bondable with 50 µm Au wire
- Low temperature firing process <450°C
- High operating temperatures (>220°C)
- Patternable, additive process for lower material costs
- Compatible with dielectric paste (AS100) and thermal via fill (AS320) pastes

PROCESSING SUMMARY

Screen type

325 mesh stainless steel screen with 12 µm emulsion buildup

Drying

Allow prints to level for 10 minutes at room temperature for >10 minutes at 150°C.

Firing

7–9 minutes @ peak temperature of 450°C with a total time of 75–90 minutes in an air atmosphere

COMPATIBILITY

Whilst DuPont has tested this composition with the materials specified above and the recommended processing conditions, it is impossible or impractical to cover every combination of materials, customer processing conditions and circuit layouts. It is therefore essential that customers thoroughly evaluate the material in their specific situations in order to completely satisfy themselves with the overall quality and suitability of the composition for its intended application(s).

STORAGE AND SHELF LIFE

Containers may be stored in a clean, stable environment at room temperature (between 5°C – 30°C) with their lids tightly sealed.

Storage in high temperature (>30°C) or in freezers (temperature <0° C) is NOT recommended as this could cause irreversible changes in the material. The shelf life of compositions in factory-sealed (unopened) containers between (5°C – 30°C) is 3 months from date of shipment.

SUBSTRATES

Substrates of different compositions and from various manufacturers may result in variations in performance properties.

Table 1-Typical Physical Properties

Test	Properties
Viscosity (Pa.s) Brookfield UC&S SC-14 @ 10 RPM, 25°C	85–115
Coverage, (cm ² /g) At total fired thickness of 14 µm	55–65
Thinner	DuPont 4553
Shelf Life (months)	3

Table 2-Typical Fired Properties

Test	Properties
Fired Thickness ¹	13-15 µm
Electrical Resistivity ¹	<1.3 m Ω /sq @25 µm thickness
Solder Adhesion ²	>15 N
Wire Bond Pull Strength ³	>25 g

Test Procedure

¹ Printed with 325 mesh stainless steel mesh/12 µm EOM, fired for 7–9 minutes @ peak temperature of 450°C with a total time of 75–90 minutes in an air atmosphere.

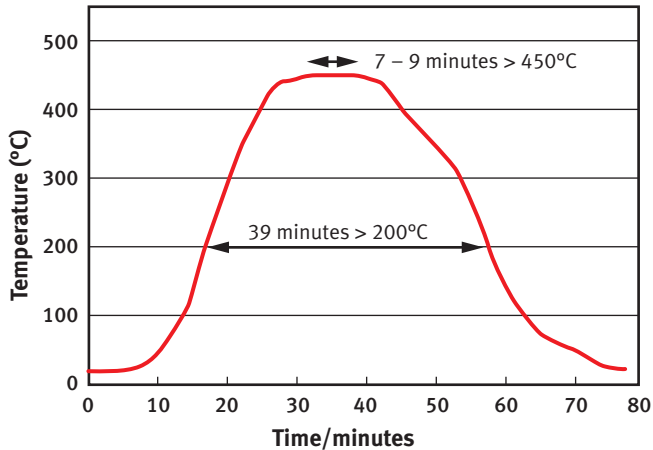
² AWG 20 tin plated copper wire, solder 95.5/3.8/0.7 (Sn/Ag/Cu), pad size 2x2 mm.

³ 50 µm Au wire. All wire breaks, no bond lifts.

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THINNER

AS300 composition is optimized for screen printing and thinning is not normally required. Use the DuPont recommended thinner for slight adjustments to viscosity or to replace evaporation losses. The use of too much thinner or the use of a non recommended thinner may affect the rheological behavior of the material and its printing characteristics. Please refer to **Table 1**.



Recommended Firing Profile

PRINTING

The composition should be thoroughly mixed before use. This is best achieved by slow, gentle hand stirring with a clean burr-free spatula (flexible plastic or stainless steel) for about 1-2 minutes. Care must be taken to avoid air entrapment. Printing should be performed in a well ventilated area. Additional information on requirements for printing areas is contained in DuPont Technical Guide EUT 7.3 'Processing-Screen Printing Rooms' available on request.

Note: optimum printing characteristics are generally achieved in the room temperature range of 20°C–23°C. It is therefore important that the material, in its container, is at the temperature prior to commencement of printing. Class 10,000 printing area is recommended for building complex hybrids and multilayer circuits, otherwise severe yield losses could occur. Refer to 'Processing Summary'.

DRYING

Allow prints to level at room temperature, then dry in a well ventilated oven or conveyor dryer. Refer to 'Processing Summary'.

FIRING

Fire in well ventilated belt, conveyor furnace or static furnace. Air flows and extraction rates should be optimized to ensure that oxidizing conditions exist within the muffle and that no exhaust gases enter the room. Full information on requirements for firing is contained in DuPont Technical Guide EUT 7.4 'Process Guide-Firing'. Refer to 'Processing Summary'.

GENERAL

Performance will depend to a large degree on care exercised in screen printing. Scrupulous care should be taken to keep the composition, printing screens and other tools free of metal contamination. Dust, lint and other particulate materials may also contribute to poor yields.

SAFETY AND HANDLING

DuPont thick film compositions are intended for use in an industrial environment by trained personnel. All appropriate health/safety regulations regarding storage, handling and processing of such materials should be complied with. For information on health/safety regulations please refer to the specific product MSDS and to the DuPont Safety Guide EUT 7.1 'Practical Safe Handling of Thick Film Compositions'.



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CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 K-28242-1 (11/14)